Claim Amendments:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently amended) A thermal interface material comprising:
a polymer component;
a phase change component mixed with the polymer component; and
greater than about 7% by weight of a non-ionic surfactant mixed with the polymer component and the phase change component.

2. (Original) The thermal interface material of claim 1, wherein the phase change component comprises a phase change wax.

3. (Original) The thermal interface material of claim 2, wherein the phase change wax comprises hydroxylated wax.

4. (Original) The thermal interface material of claim 2, wherein the phase change wax comprises between about 5% and 50% by weight of the thermal interface material.

5. (Original) The thermal interface material of claim 2, wherein the phase change wax comprises between about 10% and 35% by weight of the thermal interface material.

6. (Original) The thermal interface material of claim 1, wherein the phase change component is adapted to soften within a temperature range of 30°C to 120°C.

7. (Original) The thermal interface material of claim 1, wherein the polymer component comprises acrylic.

8. (Original) The thermal interface material of claim 1, wherein the polymer component comprises between about 5% and 25% by weight of the thermal interface material.

9. (Original) The thermal interface material of claim 1, wherein the polymer component comprises between about 9% and 23% by weight of the thermal interface material.

10. (Original) The thermal interface material of claim 1, further comprises a particulate thermally conductive filler.

11. (Original) The thermal interface material of claim 10, wherein the thermally conductive filler comprises boron nitride.

12. (Original) The thermal interface material of claim 10, wherein the thermally conductive filler comprises between about 10% and 50% by weight of the thermal interface material.

13. (Original) The thermal interface material of claim 10, wherein the thermally conductive filler comprises between about 20% and 35% by weight of the thermal interface material.

14. (Canceled)

15. (Canceled)

16. (Previously Presented) The thermal interface material of claim 1, wherein the non-ionic surfactant is derived from alkanolamide.

17. (Previously Presented) The thermal interface material of claim 1, wherein the non-ionic surfactant is derived from cocamide.

18. (Previously Presented) The thermal interface material of claim 1, wherein the non-ionic surfactant is derived from glycerin.

19. (Currently amended) The thermal interface material of claim 1, wherein ~~the surfactant comprises between about 1% to 50% by weight of~~ the thermal interface material comprises greater than about 10% by weight of the surfactant.

20. (Currently amended) The thermal interface material of claim 1, wherein ~~the surfactant comprises between about 3% to 30% by weight of~~ the thermal interface material comprises between about 14% and 25% by weight of the surfactant.

21. (Original) The thermal interface material of claim 1, wherein the polymer is an adhesive.

22. (Original) The thermal interface material of claim 21, wherein the adhesive is a pressure sensitive adhesive.

23. (Original) The thermal interface material of claim 21, wherein the adhesive comprises acrylate.

24. (Original) The thermal interface material of claim 21, wherein the adhesive comprises silicone.

25. (Currently amended) A thermal interface material comprising a phase change wax and greater than about 7% by weight of a non-ionic surfactant ~~and a phase change wax~~.

26. (Original) The thermal interface material of claim 25, wherein the phase change wax comprises between about 5% and 50% by weight of the thermal interface material.

27. (Original) The thermal interface material of claim 25, further comprising a polymer component.

28. (Original) The thermal interface material of claim 27, wherein the polymer is an adhesive.

29. (Original) The thermal interface material of claim 27, wherein the polymer component comprises between about 5% and 25% by weight of the thermal interface material.

30. (Original) The thermal interface material of claim 25, further comprising a particulate thermally conductive filler.

31. (Original) The thermal interface material of claim 30, wherein the thermally conductive filler comprises between about 10% and 50% by weight of the thermal interface material.

32. (Canceled)

33. (Previously Presented) The thermal interface material of claim 25, wherein the non-ionic surfactant is derived from alkanolamide.

34. (Previously Presented) The thermal interface material of claim 25, wherein the non-ionic surfactant is derived from glycerin.

35. (Currently amended) The thermal interface material of claim 25, wherein the ~~surfactant comprises between about 1% to 50% by weight of~~ the thermal interface material comprises greater than about 10% by weight of the surfactant.

36. (Currently amended) A thermal interface tape comprising:
a first layer comprising a conductive film; and
a second layer comprising a thermal interface material comprising ~~a non-ionic surfactant and~~ a phase change component and greater than about 7% by weight of a non-ionic surfactant.

37. (Canceled)

38. (Original) The tape of claim 36, wherein the surfactant is derived from alkanolamide.

39. (Original) The tape of claim 36, wherein the surfactant is derived from glycerin.

40. (Original) The tape of claim 36, wherein the thermal interface material comprises a thermally conductive filler.

41. (Original) The tape of claim 36, wherein the second layer is coupled to a protective barrier.

42. (Currently amended) A microelectronic structure comprising:
an integrated circuit active device;
a heat sink; and
a thermal interface tape comprising greater than about 7% by weight of a non-ionic surfactant and comprising a phase change component, the thermal interface tape disposed between and coupling the integrated circuit active device and the heat sink to each other.

43.-50. (Canceled)

51. (Currently amended) A thermal interface material comprising a phase change component, greater than about 7% by weight of a non-ionic surfactant, and a thermally conductive filler, wherein the thermal impedance of the thermal interface material is ≤ 0.8 x wherein x is the thermal impedance of a comparative thermal interface material having the same composition of the thermal interface material, but containing no surfactant.

52. (Currently amended) A thermal interface tape comprising:
a first layer comprising a conductive film; and
a second layer comprising a thermal interface material coupled to the first layer, the second layer comprising greater than about 7% by weight of a non-ionic surfactant, a phase change component, a polymer, and thermally conductive filler, the thermal interface material having a wetting angle of not more than about 80 degrees and a thermal impedance of no more than about 0.115 °C in^2/W, at an operating temperature, wherein the thermal impedance of the thermal interface

material is ≤ 0.8 x wherein x is the thermal impedance of a comparative thermal interface material having the same composition of the thermal interface material, but containing no surfactant.

53. (Newly added) A thermal interface material comprising a phase change wax and greater than about 7% by weight of a surfactant.